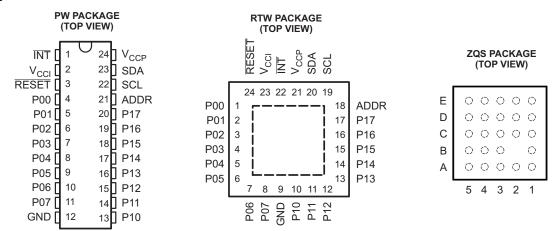
# LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER TRUMENTS WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS

SCPS153-DECEMBER 2007

## **FEATURES**

- **Operating Power-Supply Voltage Range of** 1.65 V to 5.5 V
- **Allows Bidirectional Voltage-Level Translation** and GPIO Expansion Between:
  - 1.8-V SCL/SDA and 1.8-V, 2.5-V, 3.3-V, or 5-V P Port
  - 2.5-V SCL/SDA and 1.8-V, 2.5-V, 3.3-V, or 5-V P Port
  - 3.3-V SCL/SDA and 1.8-V, 2.5-V, 3.3-V, or 5-V P Port
  - 5-V SCL/SDA and 1.8-V, 2.5-V, 3.3-V, or 5-V P Port
- I<sup>2</sup>C to Parallel Port Expander
- Low Standby Current Consumption of 1 µA
- Schmitt-Trigger Action Allows Slow Input Transition and Better Switching Noise Immunity at the SCL and SDA Inputs
  - $V_{hvs} = 0.18 \text{ V Typ at } 1.8 \text{ V}$
  - $V_{hvs} = 0.25 \text{ V Typ at } 2.5 \text{ V}$
  - $V_{hys} = 0.33 \text{ V Typ at } 3.3 \text{ V}$
  - $V_{hvs} = 0.5 V Typ at 5 V$

- 5-V Tolerant I/O Ports
- Active-Low Reset Input (RESET)
- **Open-Drain Active-Low Interrupt Output (INT)**
- 400-kHz Fast I<sup>2</sup>C Bus
- Input/Output Configuration Register
- **Polarity Inversion Register**
- **Internal Power-On Reset**
- Power Up With All Channels Configured as Inputs
- No Glitch On Power Up
- Noise Filter on SCL/SDA Inputs
- **Latched Outputs With High-Current Drive Maximum Capability for Directly Driving LEDs**
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22** 
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



# **DESCRIPTION/ORDERING INFORMATION**

This 16-bit I/O expander for the two-line bidirectional bus (I<sup>2</sup>C) is designed to provide general-purpose remote I/O expansion for most microcontroller families via the I<sup>2</sup>C interface [serial clock (SCL) and serial data (SDA)].

The major benefit of this device is its wide V<sub>CC</sub> range. It can operate from 1.65 V to 5.5 V on the P-port side and on the SDA/SCL side. This allows the TCA6416 to interface with next-generation microprocessors and microcontrollers on the SDA/SCL side, where supply levels are dropping down to conserve power. In contrast to the dropping power supplies of microprocessors and microcontrollers, some PCB components, such as LEDs, remain at a 5-V power supply.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# **TCA6416** LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS



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# DESCRIPTION/ORDERING INFORMATION (CONTINUED)

#### ORDERING INFORMATION

T <sub>A</sub>	PACKA	GE <sup>(1)(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	BGA – ZQS (Pb-free)	Reel of 1000	TCA6416ZQSR	PH416	
–40°C to 85°C	QFN – RTW	Reel of 3000	TCA6416RTWR	PREVIEW	
-40 C to 65 C	TOOOD DW	Tube of 70	TCA6416PW	DUMAG	
	TSSOP – PW	Reel of 2000	TCA6416PWR	PH416	

Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

The bidirectional voltage level translation in the TCA6416 is provided through  $V_{CCI}$ .  $V_{CCI}$  should be connected to the  $V_{CC}$  of the external SCL/SDA lines. This indicates the  $V_{CC}$  level of the I<sup>2</sup>C bus to the TCA6416. The voltage level on the P-port of the TCA6416 is determined by the V<sub>CCP</sub>.

The TCA6416 consists of two 8-bit Configuration (input or output selection), Input, Output, and Polarity Inversion (active high) registers. At power on, the I/Os are configured as inputs. However, the system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding input or output register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system master.

The system master can reset the TCA6416 in the event of a timeout or other improper operation by asserting a low in the RESET input. The power-on reset puts the registers in their default state and initializes the I<sup>2</sup>C/SMBus state machine. The RESET pin causes the same reset/initialization to occur without depowering the part.

The TCA6416 open-drain interrupt (INT) output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed.

INT can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I<sup>2</sup>C bus. Thus, the TCA6416 can remain a simple slave device.

The device P-port outputs have high-current sink capabilities for directly driving LEDs while consuming low device current.

One hardware pin (ADDR) can be used to program and vary the fixed I<sup>2</sup>C address and allow up to two devices to share the same I<sup>2</sup>C bus or SMBus.

# **ZQS Package Terminal Assignments**

	5	4	3	2	1
Α	SCL	SDA	ĪNT	RESET	P00
В	ADDR	V <sub>CCP</sub>	V <sub>CCI</sub>	NB	P02
С	P16	P17	P01	P04	P03
D	P15	P14	P12	P07	P05
E	P13	P11	P10	GND	P06

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



# 

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# **TERMINAL FUNCTIONS**

	TERMINAL			
	NO.			DESCRIPTION
TSSOP (PW)	QFN (RTW)	BGA (ZQS)	NAME	DESCRIPTION
1	22	А3	ĪNT	Interrupt output. Connect to V <sub>CCI</sub> or V <sub>CCP</sub> through a pullup resistor.
2	23	В3	V <sub>CCI</sub>	Supply voltage of $I^2C$ bus. Connect directly to the $V_{CC}$ of the external $I^2C$ master. Provides voltage-level translation.
3	24	A2	RESET	Active-low reset input. Connect to V <sub>CCP</sub> through a pullup resistor, if no active connection is used.
4	1	A1	P00	P-port input/output (push-pull design structure). At power on, P00 is configured as an input.
5	2	C3	P01	P-port input/output (push-pull design structure). At power on, P01 is configured as an input.
6	3	B1	P02	P-port input/output (push-pull design structure). At power on, P02 is configured as an input.
7	4	C1	P03	P-port input/output (push-pull design structure). At power on, P03 is configured as an input.
8	5	C2	P04	P-port input/output (push-pull design structure). At power on, P04 is configured as an input.
9	6	D1	P05	P-port input/output (push-pull design structure). At power on, P05 is configured as an input.
10	7	E1	P06	P-port input/output (push-pull design structure). At power on, P06 is configured as an input.
11	8	D2	P07	P-port input/output (push-pull design structure). At power on, P07 is configured as an input.
12	9	E2	GND	Ground
13	10	E3	P10	P-port input/output (push-pull design structure). At power on, P10 is configured as an input.
14	11	E4	P11	P-port input/output (push-pull design structure). At power on, P11 is configured as an input.
15	12	D3	P12	P-port input/output (push-pull design structure). At power on, P12 is configured as an input.
16	13	E5	P13	P-port input/output (push-pull design structure). At power on, P13 is configured as an input.
17	14	D4	P14	P-port input/output (push-pull design structure). At power on, P14 is configured as an input.
18	15	D5	P15	P-port input/output (push-pull design structure). At power on, P15 is configured as an input.
19	16	C5	P16	P-port input/output (push-pull design structure). At power on, P16 is configured as an input.
20	17	C4	P17	P-port input/output (push-pull design structure). At power on, P17 is configured as an input.
21	18	B5	ADDR	Address input. Connect directly to V <sub>CCP</sub> or ground.
22	19	A5	SCL	Serial clock bus. Connect to V <sub>CCI</sub> through a pullup resistor.
23	20	A4	SDA	Serial data bus. Connect to V <sub>CCI</sub> through a pullup resistor.
24	21	B4	$V_{CCP}$	Supply voltage of TCA6416 for P port

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# TCA6416 LOW-VOLTAGE 16-BIT I $^2$ C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS



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# **Voltage Translation**

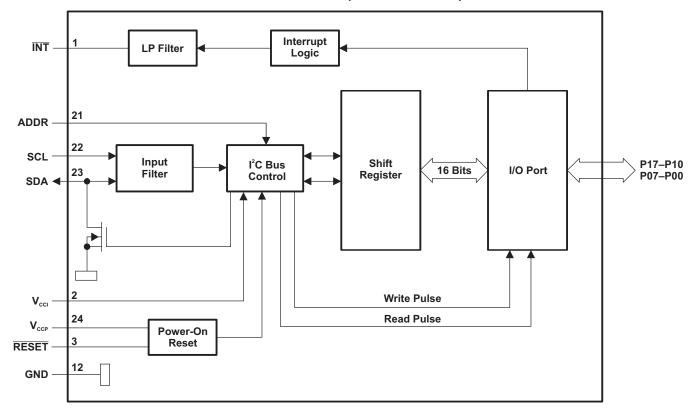
Table 1 shows how to set up  $V_{CC}$  levels for the necessary voltage translation between the  $I^2C$  bus and the TCA6416.

**Table 1. Voltage Translation** 

V <sub>CCI</sub> (SDA AND SCL OF I <sup>2</sup> C MASTER) (V)	V <sub>CCP</sub> (P PORT) (V)
1.8	1.8
1.8	2.5
1.8	3.3
1.8	5
2.5	1.8
2.5	2.5
2.5	3.3
2.5	5
3.3	1.8
3.3	2.5
3.3	3.3
3.3	5
5	1.8
5	2.5
5	3.3
5	5



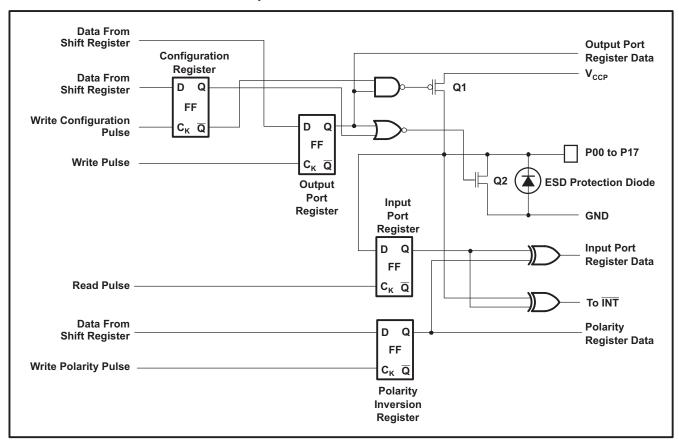
# **LOGIC DIAGRAM (POSITIVE LOGIC)**



- A. All I/Os are set to inputs at reset.
- B. Pin numbers shown are for the PW package.



# Simplified Schematic of P0 to P17



A. On power up or reset, all registers return to default values.

# I/O Port

When an I/O is configured as an input, FETs Q1 and Q2 are off, which creates a high-impedance input. The input voltage may be raised above  $V_{CC}$  to a maximum of 5.5 V.

If the I/O is configured as an output, Q1 or Q2 is enabled, depending on the state of the output port register. In this case, there are low-impedance paths between the I/O pin and either  $V_{CC}$  or GND. The external voltage applied to this I/O pin should not exceed the recommended levels for proper operation.

# I<sup>2</sup>C Interface

The bidirectional I<sup>2</sup>C bus consists of the serial clock (SCL) and serial data (SDA) lines. Both lines must be connected to a positive supply through a pullup resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

 $I^2C$  communication with this device is initiated by a master sending a Start condition, a high-to-low transition on the SDA input/output, while the SCL input is high (see Figure 1). After the Start condition, the device address byte is sent, most significant bit (MSB) first, including the data direction bit (R/W).

After receiving the valid address byte, this device responds with an acknowledge (ACK), a low on the SDA input/output during the high of the ACK-related clock pulse. The address (ADDR) input of the slave device must not be changed between the Start and the Stop conditions.

On the I<sup>2</sup>C bus, only one data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high pulse of the clock period, as changes in the data line at this time are interpreted as control commands (Start or Stop) (see Figure 2).



# LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS

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A Stop condition, a low-to-high transition on the SDA input/output while the SCL input is high, is sent by the master (see Figure 1).

Any number of data bytes can be transferred from the transmitter to receiver between the Start and the Stop conditions. Each byte of eight bits is followed by one ACK bit. The transmitter must release the SDA line before the receiver can send an ACK bit. The device that acknowledges must pull down the SDA line during the ACK clock pulse, so that the SDA line is stable low during the high pulse of the ACK-related clock period (see Figure 3). When a slave receiver is addressed, it must generate an ACK after each byte is received. Similarly, the master must generate an ACK after each byte that it receives from the slave transmitter. Setup and hold times must be met to ensure proper operation.

A master receiver signals an end of data to the slave transmitter by not generating an acknowledge (NACK) after the last byte has been clocked out of the slave. This is done by the master receiver by holding the SDA line high. In this event, the transmitter must release the data line to enable the master to generate a Stop condition.

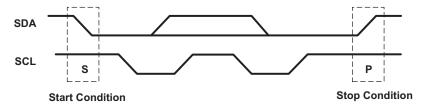


Figure 1. Definition of Start and Stop Conditions

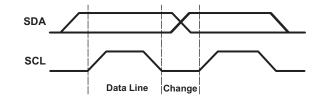


Figure 2. Bit Transfer

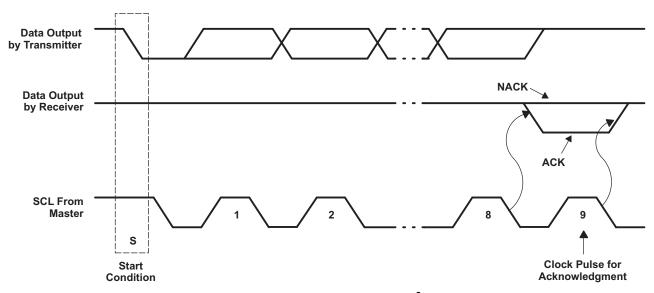


Figure 3. Acknowledgment on the I<sup>2</sup>C Bus

# TCA6416 LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS

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## Interface Definition

ВҮТЕ		BIT						
	7 (MSB)	6	5	4	3	2	1	0 (LSB)
I <sup>2</sup> C slave address	L	Н	L	L	L	L	ADDR	R/W
I/O data hua	P07	P06	P05	P04	P03	P02	P01	P00
I/O data bus	P17	P16	P15	P14	P13	P12	P11	P10

#### **Device Address**

The address of the TCA6416 is shown in Figure 4.

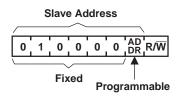


Figure 4. TCA6416 Address

# **Address Reference**

ADDR	I <sup>2</sup> C BUS SLAVE ADDRESS
L	32 (decimal), 20 (hexadecimal)
Н	33 (decimal), 21 (hexadecimal)

The last bit of the slave address defines the operation (read or write) to be performed. A high (1) selects a read operation, while a low (0) selects a write operation.

# **Control Register and Command Byte**

Following the successful acknowledgment of the address byte, the bus master sends a command byte, which is stored in the control register in the TCA6416. Three bits of this data byte state the operation (read or write) and the internal registers (input, output, polarity inversion, or configuration) that will be affected. This register can be written or read through the I<sup>2</sup>C bus. The command byte is sent only during a write transmission.

Once a new command has been sent, the register that was addressed continues to be accessed by reads until a new command byte has been sent.

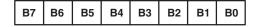


Figure 5. Control Register Bits

# **Command Byte**

	(	CONTR	OL RE	GISTE	R BITS	3		COMMAND BYTE	DECICTED	PROTOCOL	POWER-UP	
B7	В6	B5	В4	В3	B2	B1	В0	(HEX)	REGISTER	PROTOCOL	DEFAULT	
0	0	0	0	0	0	0	0	00	Input Port 0	Read byte	xxxx xxxx <sup>(1)</sup>	
0	0	0	0	0	0	0	1	01	Input Port 1	Read byte	xxxx xxxx	
0	0	0	0	0	0	1	0	02	Output Port 0	Read/write byte	1111 1111	
0	0	0	0	0	0	1	1	03	Output Port 1	Read/write byte	1111 1111	
0	0	0	0	0	1	0	0	04	Polarity Inversion Port 0	Read/write byte	0000 0000	
0	0	0	0	0	1	0	1	05	Polarity Inversion Port 1	Read/write byte	0000 0000	
0	0	0	0	0	1	1	0	06 Configuration Port 0 Read/write byte		1111 1111		
0	0	0	0	0	1	1	1	07	Configuration Port 1	Read/write byte	1111 1111	

(1) Undefined

# LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS

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# **Register Descriptions**

The Input Port registers (registers 0 and 1) reflect the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration register. They act only on read operation. Writes to these registers have no effect. The default value (X) is determined by the externally applied logic level. Before a read operation, a write transmission is sent with the command byte to indicate to the I<sup>2</sup>C device that the Input Port register will be accessed next.

# Registers 0 and 1 (Input Port Registers)

BIT	I-07	I-06	I-05	I-04	I-03	I-02	I-01	I-00
DEFAULT	Х	Х	Х	Х	X	Х	Х	X
BIT	I-17	I-16	I-15	I-14	I-13	I-12	I-11	I-10
DEFAULT	Х	Х	Х	Х	Х	Х	Х	Х

The Output Port registers (registers 2 and 3) shows the outgoing logic levels of the pins defined as outputs by the Configuration register. Bit values in these registers have no effect on pins defined as inputs. In turn, reads from these registers reflect the value that is in the flip-flop controlling the output selection, NOT the actual pin value.

# Registers 2 and 3 (Output Port Registers)

BIT	O-07	O-06	O-05	O-04	O-03	O-02	O-01	O-00
DEFAULT	1	1	1	1	1	1	1	1
BIT	O-17	O-16	O-15	O-14	O-13	O-12	O-11	O-10
DEFAULT	1	1	1	1	1	1	1	1

The Polarity Inversion registers (register 4 and 5) allow polarity inversion of pins defined as inputs by the Configuration register. If a bit in these registers is set (written with 1), the corresponding port pin's polarity is inverted. If a bit in these registers is cleared (written with a 0), the corresponding port pin's original polarity is retained.

# Registers 4 and 5 (Polarity Inversion Registers)

BIT	P-07	P-06	P-05	P-04	P-03	P-02	P-01	P-00
DEFAULT	0	0	0	0	0	0	0	0
BIT	P-17	P-16	P-15	P-14	P-13	P-12	P-11	P-10
DEFAULT	0	0	0	0	0	0	0	0

The Configuration registers (registers 6 and 7) configure the direction of the I/O pins. If a bit in these registers is set to 1, the corresponding port pin is enabled as an input with a high-impedance output driver. If a bit in these registers is cleared to 0, the corresponding port pin is enabled as an output.

### Registers 6 and 7 (Configuration Registers)

BIT	C-07	C-06	C-05	C-04	C-03	C-02	C-01	C-00
DEFAULT	1	1	1	1	1	1	1	1
BIT	C-17	C-16	C-15	C-14	C-13	C-12	C-11	C-10
DEFAULT	1	1	1	1	1	1	1	1

# **Power-On Reset**

When power (from 0 V) is applied to V<sub>CCP</sub>, an internal power-on reset holds the TCA6416 in a reset condition until V<sub>CCP</sub> has reached V<sub>POR</sub>. At that time, the reset condition is released, and the TCA6416 registers and I<sup>2</sup>C/SMBus state machine initializes to their default states. After that, V<sub>CCP</sub> must be lowered to below 0.2 V and back up to the operating voltage for a power-reset cycle.

# TCA6416 LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS



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# Reset Input (RESET)

The  $\overline{\text{RESET}}$  input can be asserted to initialize the system while keeping the  $V_{CCP}$  at its operating level. A reset can be accomplished by holding the  $\overline{\text{RESET}}$  pin low for a minimum of  $t_W$ . The  $\overline{\text{TCA6416}}$  registers and  $I^2C/SMBus$  state machine are changed to their default state once  $\overline{\text{RESET}}$  is low (0). When  $\overline{\text{RESET}}$  is high (1), the I/O levels at the P port can be changed externally or through the master. This input requires a pullup resistor to  $V_{CCP}$ , if no active connection is used.

# **Interrupt Output (INT)**

An interrupt is generated by any rising or falling edge of the port inputs in the input mode. After time  $t_{iv}$ , the signal  $\overline{INT}$  is valid. Resetting the interrupt circuit is achieved when data on the port is changed to the original setting, data is read from the port that generated the interrupt or in a Stop event. Resetting occurs in the read mode at the acknowledge (ACK) or not acknowledge (NACK) bit after the rising edge of the SCL signal. In a Stop event,  $\overline{INT}$  is cleared after the rising edge of SDA. Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the resetting of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as  $\overline{INT}$ .

Reading from or writing to another device does not affect the interrupt circuit, and a pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur, if the state of the pin does not match the contents of the Input Port register.

The  $\overline{\text{INT}}$  output has an open-drain structure and requires pullup resistor to  $V_{\text{CCP}}$  or  $V_{\text{CCI}}$  depending on the application. If the  $\overline{\text{INT}}$  signal is connected back to the processor that provides the SCL signal to the TCA6408, then the  $\overline{\text{INT}}$  pin has to be connected to  $V_{\text{CCI}}$ . If not, the  $\overline{\text{INT}}$  pin can be connected to  $V_{\text{CCP}}$ .

#### **Bus Transactions**

Data is exchanged between the master and TCA6416 through write and read commands.

#### Writes

Data is transmitted to the TCA6416 by sending the device address and setting the least-significant bit (LSB) to a logic 0 (see Figure 4 for device address). The command byte is sent after the address and determines which register receives the data that follows the command byte. There is no limitation on the number of data bytes sent in one write transmission.

The eight registers within the TCA6416 are configured to operate as four register pairs. The four pairs are input ports, output ports, polarity inversion ports and configuration ports. After sending data to one register, the next data byte is sent to the other register in the pair (see Figure 6 and Figure 7). For example, if the first byte is send to Output Port 1 (register 3), the next byte is stored in Output Port 0 (register 2).

There is no limitation on the number of data bytes sent in one write transmission. In this way, each 8-bit register may be updated independently of the other registers.

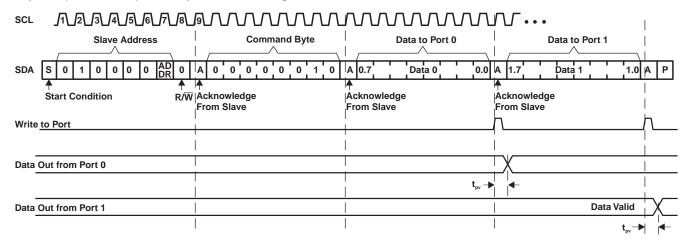


Figure 6. Write to Output Port Register

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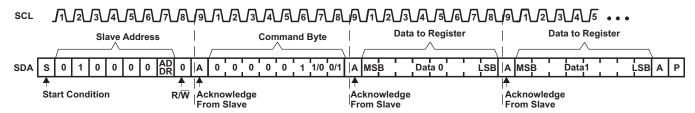


Figure 7. Write to Configuration or Polarity Inversion Registers

## Reads

The bus master first must send the TCA6416 address with the LSB set to a logic 0 (see Figure 4 for device address). The command byte is sent after the address and determines which register is accessed.

After a restart, the device address is sent again but, this time, the LSB is set to a logic 1. Data from the register defined by the command byte then is sent by the TCA6416 (see Figure 8 and Figure 9).

After a restart, the value of the register defined by the command byte matches the register being accessed when the restart occurred. For example, if the command byte references Input Port 1 before the restart, and the restart occurs when Input Port 0 is being read, the stored command byte changes to reference Input Port 0. The original command byte is forgotten. If a subsequent restart occurs, Input Port 0 is read first. Data is clocked into the register on the rising edge of the ACK clock pulse. After the first byte is read, additional bytes may be read, but the data now reflects the information in the other register in the pair. For example, if Input Port 1 is read, the next byte read is Input Port 0.

Data is clocked into the register on the rising edge of the ACK clock pulse. There is no limitation on the number of data bytes received in one read transmission, but when the final byte is received, the bus master must not acknowledge the data.

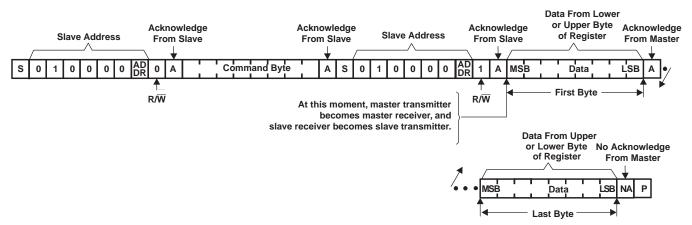
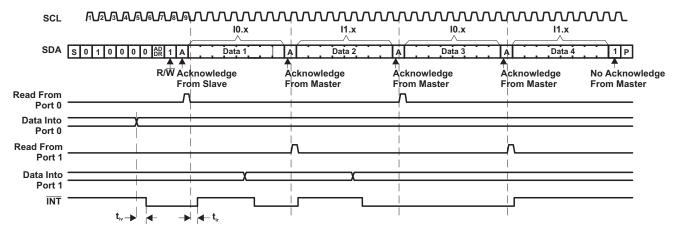


Figure 8. Read From Register

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- Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port register).
- This figure eliminates the command byte transfer, a restart, and slave address call between the initial slave address call and actual data transfer from P port (see Figure 8).

Figure 9. Read Input Port Register



# TCA6416 LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS

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# ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT	
V <sub>CCI</sub>	Supply voltage range			-0.5	6.5	V	
V <sub>CCP</sub>	Supply voltage range			-0.5	6.5	V	
VI	Input voltage range (2)			-0.5	6.5	V	
Vo	Output voltage range <sup>(2)</sup>			-0.5	6.5	V	
I <sub>IK</sub>	Input clamp current	ADDR, RESET, SCL	V <sub>I</sub> < 0		±20	mA	
I <sub>OK</sub>	Output clamp current	ĪNT	V <sub>O</sub> < 0		±20	mA	
	Input/output clamp current	P port	$V_O < 0$ or $V_O > V_{CCP}$	±20		mA	
I <sub>IOK</sub>	input/output clamp current	SDA	$V_O < 0$ or $V_O > V_{CCI}$		±20	ША	
	Continuous output low current	P port $V_0 = 0$ to $V_{CCP}$			25	mA	
l <sub>OL</sub>	Continuous output low current	SDA, ĪNT	$V_O = 0$ to $V_{CCI}$		15	ША	
$I_{OH}$	Continuous output high current	P port	$V_O = 0$ to $V_{CCP}$		25	mA	
	Continuous current through GND				200		
$I_{CC}$	Continuous current through V <sub>CCF</sub>				160	mA	
	Continuous current through V <sub>CCI</sub>				10		
			PW package		88	°C/W	
$\theta_{JA}$	Package thermal impedance (3)		RTW package		66		
			TBD				
T <sub>stg</sub>	Storage temperature range			-65	150	°C	

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# RECOMMENDED OPERATING CONDITIONS

			MIN	MAX	UNIT
V <sub>CCI</sub>	Supply voltage	Supply voltage			
$V_{CCP}$	Supply voltage		1.65	5.5	V
V <sub>IH</sub>	Lligh lovel input veltage	SCL, SDA	0.7 × V <sub>CCI</sub>	5.5	V
	High-level input voltage	ADDR, P17-P00, RESET	$0.7 \times V_{CCP}$	5.5	V
\/	Low level input voltage	SCL, SDA	-0.5	$0.3 \times V_{CCI}$	V
$V_{IL}$	Low-level input voltage	ADDR, P17–P00, RESET	-0.5	$0.3 \times V_{CCP}$	V
I <sub>OH</sub>	High-level output current	P17-P00		10	mA
I <sub>OL</sub>	Low-level output current	P17-P00		25	mA
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

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<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# TCA6416 LOW-VOLTAGE 16-BIT I $^2$ C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS



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# **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range, V<sub>CCI</sub> = 1.65 V to 5.5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CCP</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>IK</sub>	Input diode clamp voltage	I <sub>I</sub> = -18 mA	1.65 V to 5.5 V	-1.2			V
V <sub>POR</sub>	Power-on reset voltage	$V_I = V_{CCP}$ or GND, $I_O = 0$	1.65 V to 5.5 V		1	1.4	V
			1.65 V	1.2			
		1 - 9 mA	2.3 V	1.8			
		$I_{OH} = -8 \text{ mA}$	3 V	2.6			
\	P-port high-level		4.5 V	4.1			V
V <sub>OH</sub>	output voltage		1.65 V	1			V
		1 - 10 mA	2.3 V	1.7			
		$I_{OH} = -10 \text{ mA}$	3 V	2.5			
			4.5 V	4.0			
			1.65 V			0.45	
		J 0 A	2.3 V			0.25	
		I <sub>OL</sub> = 8 mA	3 V			0.25	
,	P-port low-level output voltage		4.5 V			0.23	
/ <sub>OL</sub>			1.65 V			0.6	V
			2.3 V			0.3	
		I <sub>OL</sub> = 10 mA	3 V			0.25	
			4.5 V			0.24	
	SDA	V <sub>OL</sub> = 0.4 V	1.65 V to 5.5 V	3			
OL	ĪNT	V <sub>OL</sub> = 0.4 V	1.65 V to 5.5 V	3	15		mA
	SCL, SDA	V <sub>I</sub> = V <sub>CCI</sub> or GND				±0.1	
I	ADDR, RESET	V <sub>I</sub> = V <sub>CCP</sub> or GND	1.65 V to 5.5 V			±0.1	μΑ
Ін	P port	$V_I = V_{CCP}$				1	μΑ
IL	P port	V <sub>I</sub> = GND	1.65 V to 5.5 V			1	μΑ
	SDA, P port, ADDR, RESET	$\begin{aligned} &V_{I} \text{ on SDA} = V_{CCI} \text{ or GND,} \\ &V_{I} \text{ on P port, ADDR and} \\ &\overline{\text{RESET}} = V_{CCP}, \\ &I_{O} = 0, \text{ I/O} = \text{inputs,} \\ &f_{SCL} = 400 \text{ kHz} \end{aligned}$	1.65 V to 5.5 V		7.8	30	
lcc (I <sub>CCI</sub> + I <sub>CCP</sub> )	SDA, P port, ADDR, RESET	$\begin{aligned} &V_{I} \text{ on SDA} = V_{CCI} \text{ or GND,} \\ &V_{I} \text{ on P port, ADDR and} \\ &\overline{\text{RESET}} = V_{CCP}, \\ &I_{O} = 0, \text{ I/O} = \text{inputs,} \\ &f_{SCL} = 100 \text{ kHz} \end{aligned}$	1.65 V to 5.5 V		1.7	10	μΑ
	SCL, SDA, P port, ADDR, RESET	$\begin{aligned} &V_{I} \text{ on SCL and SDA} = V_{CCI} \text{ or GND,} \\ &V_{I} \text{ on P port, ADDR and} \\ &RESET = V_{CCP}, \\ &I_{O} = 0, \text{ I/O} = \text{inputs,} \\ &f_{SCL} = 0 \end{aligned}$	1.65 V to 5.5 V		0.1	2	
ΔI <sub>CCI</sub>	SCL, SDA	One input at V <sub>CCI</sub> – 0.6 V, Other inputs at V <sub>CCI</sub> or GND	4051/4-551/			25	^
ΔI <sub>CCP</sub>	P port, ADDR, RESET	One input at V <sub>CCP</sub> – 0.6 V, Other inputs at V <sub>CCP</sub> or GND	1.65 V to 5.5 V			60	μА
C <sub>I</sub>	SCL	V <sub>I</sub> = V <sub>CCI</sub> or GND	1.65 V to 5.5 V		6	7	pF
	SDA	V <sub>IO</sub> = V <sub>CCI</sub> or GND	1.65 V to 5.5 V		7	8	
$C_{io}$	P port				7.5	8.5	pF

<sup>(1)</sup> Except for  $I_{CC}$ , all typical values are at nominal supply voltage (1.8-V, 2.5-V, 3.3-V, or 5-V  $V_{CC}$ ) and  $T_A = 25^{\circ}C$ . For  $I_{CC}$ , the typical values are at  $V_{CCP} = V_{CCI} = 3.3$  V and  $T_A = 25^{\circ}C$ .

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# LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS

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# I<sup>2</sup>C INTERFACE TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 10)

		STANDARE I <sup>2</sup> C BU		FAST MODE I <sup>2</sup> C BUS	<b>E</b>	UNIT
		MIN	MAX	MIN	MAX	
f <sub>scl</sub>	I <sup>2</sup> C clock frequency	0	100	0	400	kHz
t <sub>sch</sub>	I <sup>2</sup> C clock high time	4		0.6		μs
t <sub>scl</sub>	I <sup>2</sup> C clock low time	4.7		1.3		μs
t <sub>sp</sub>	I <sup>2</sup> C spike time	0	50	0	50	ns
t <sub>sds</sub>	I <sup>2</sup> C serial data setup time	250		100		ns
t <sub>sdh</sub>	I <sup>2</sup> C serial data hold time	0		0		ns
t <sub>icr</sub>	I <sup>2</sup> C input rise time		1000	20 + 0.1C <sub>b</sub> <sup>(1)</sup>	300	ns
t <sub>icf</sub>	I <sup>2</sup> C input fall time		300	20 + 0.1C <sub>b</sub> <sup>(1)</sup>	300	ns
t <sub>ocf</sub>	I <sup>2</sup> C output fall time; 10 pF to 400 pF bus		300	20 + 0.1C <sub>b</sub> <sup>(1)</sup>	300	μs
t <sub>buf</sub>	I <sup>2</sup> C bus free time between Stop and Start	4.7		1.3		μs
t <sub>sts</sub>	I <sup>2</sup> C Start or repeater Start condition setup time	4.7		0.6		μs
t <sub>sth</sub>	I <sup>2</sup> C Start or repeater Start condition hold time	4		0.6		μs
t <sub>sps</sub>	I <sup>2</sup> C Stop condition setup time	4		0.6		μs
t <sub>vd(data)</sub>	Valid data time; SCL low to SDA output valid		1		1	μs
t <sub>vd(ack)</sub>	Valid data time of ACK condition; ACK signal from SCL low to SDA (out) low		1		1	μs

<sup>(1)</sup> C<sub>b</sub> = total capacitance of one bus line in pF

# **RESET TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 13)

		STANDARD MODE I <sup>2</sup> C BUS		FAST MC I <sup>2</sup> C BU	UNIT	
		MIN	MAX	MIN	MAX	
t <sub>W</sub>	Reset pulse duration	4		4		ns
t <sub>REC</sub>	Reset recovery time	0		0		ns
t <sub>RESET</sub>	Time to reset <sup>(1)</sup>	600		600		ns

(1) Minimum time for SDA to become high or minimum time to wait before doing a START

# TCA6416 LOW-VOLTAGE 16-BIT $I^2$ C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS



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# **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range,  $C_L \le 100 \text{ pF}$  (unless otherwise noted) (see Figure 10)

	PARAMETER	FROM	то	STANDARD MODE I <sup>2</sup> C BUS	FAST MODE I <sup>2</sup> C BUS	UNIT
				MIN MAX	MIN MAX	
t <sub>IV</sub>	Interrupt valid time	P port	ĪNT	4	4	μs
t <sub>IR</sub>	Interrupt reset delay time	SCL	ĪNT	4	4	μs
$t_{\text{PV}}$	Output data valid	SCL	P7-P0	400	400	ns
$t_{PS}$	Input data setup time	P port	SCL	0	0	ns
$t_{PH}$	Input data hold time	P port	SCL	300	300	ns

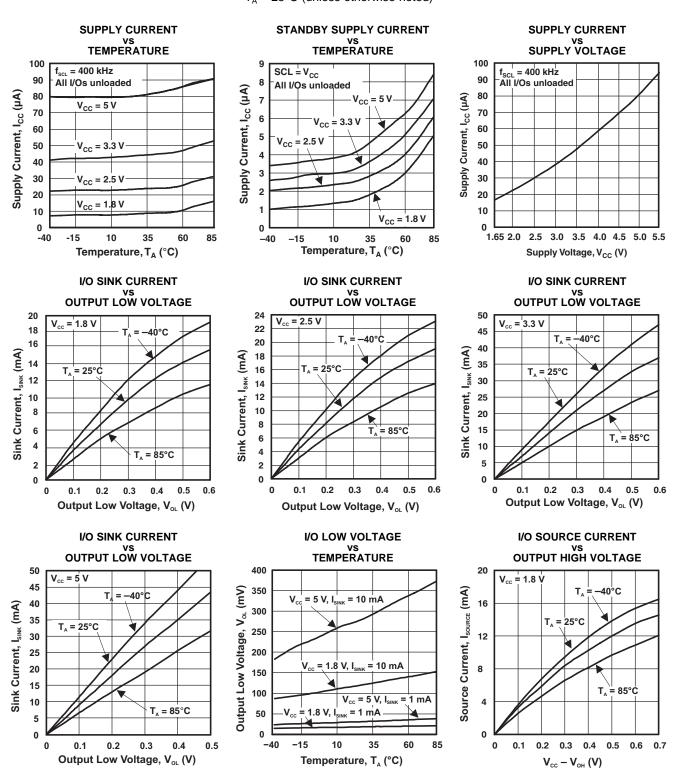
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# TYPICAL CHARACTERISTICS

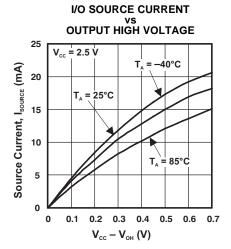
 $T_A = 25^{\circ}C$  (unless otherwise noted)

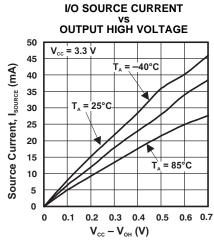


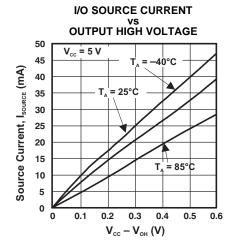


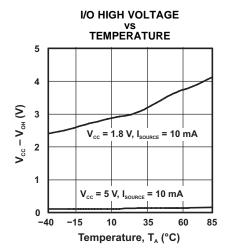
# **TYPICAL CHARACTERISTICS (continued)**

 $T_A = 25^{\circ}C$  (unless otherwise noted)





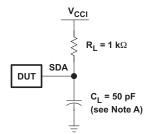




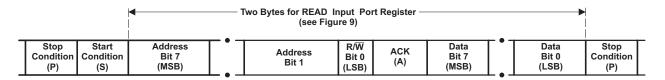
**PRODUCT PREVIEW** 

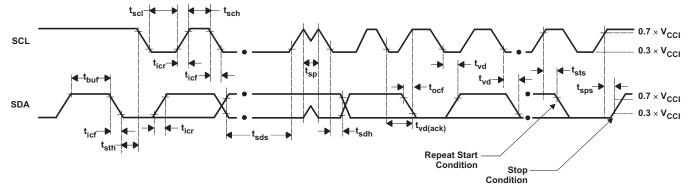


# PARAMETER MEASUREMENT INFORMATION



SDA LOAD CONFIGURATION





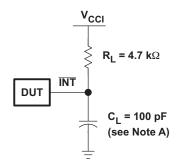
**VOLTAGE WAVEFORMS** 

BYTE	DESCRIPTION
1	I <sup>2</sup> C address
2	Input register port data

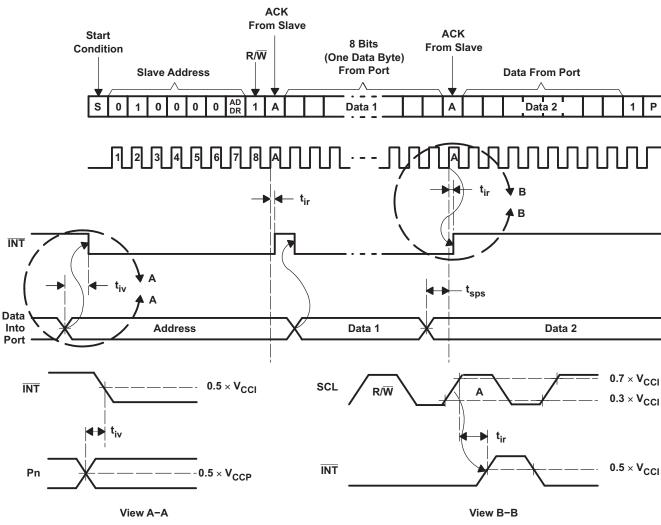
- A. C<sub>L</sub> includes probe and jig capacitance. tocf is measured with C<sub>L</sub> of 10 pF or 400 pF.
- B. All inputs are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_r/t_f \leq$  30 ns.
- C. All parameters and waveforms are not applicable to all devices.

Figure 10. I<sup>2</sup>C Interface Load Circuit and Voltage Waveforms

# **PARAMETER MEASUREMENT INFORMATION (continued)**



#### INTERRUPT LOAD CONFIGURATION



- A. C<sub>L</sub> includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_r/t_f \leq$  30 ns.
- C. All parameters and waveforms are not applicable to all devices.

Figure 11. Interrupt Load Circuit and Voltage Waveforms

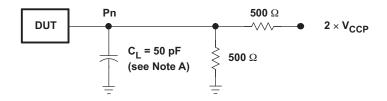
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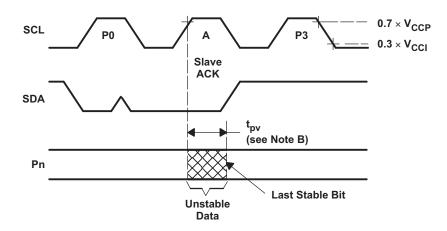
PRODUCT PREVIEW



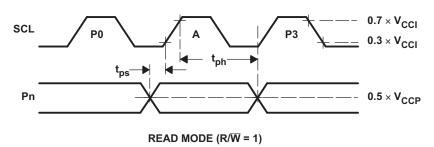
# PARAMETER MEASUREMENT INFORMATION (continued)



#### P PORT LOAD CONFIGURATION



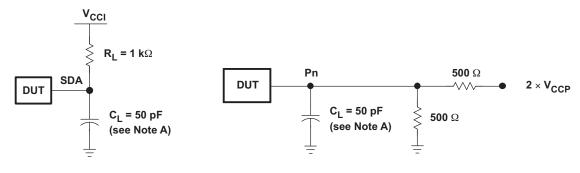
WRITE MODE  $(R/\overline{W} = 0)$ 



- A.  $C_L$  includes probe and jig capacitance.
- B.  $t_{pv}$  is measured from  $0.7 \times V_{CC}$  on SCL to 50% I/O (Pn) output.
- C. All inputs are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_r/t_f \leq$  30 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

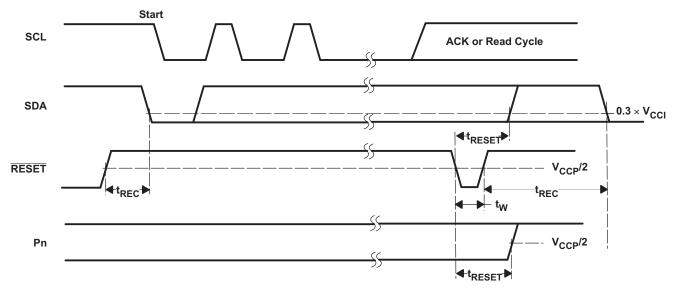
Figure 12. P Port Load Circuit and Timing Waveforms

# PARAMETER MEASUREMENT INFORMATION (continued)



**SDA LOAD CONFIGURATION** 

P PORT LOAD CONFIGURATION



- A. C<sub>L</sub> includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r/t_f \leq$  30 ns.
- C. The outputs are measured one at a time, with one transition per measurement.
- D. I/Os are configured as inputs.
- E. All parameters and waveforms are not applicable to all devices.

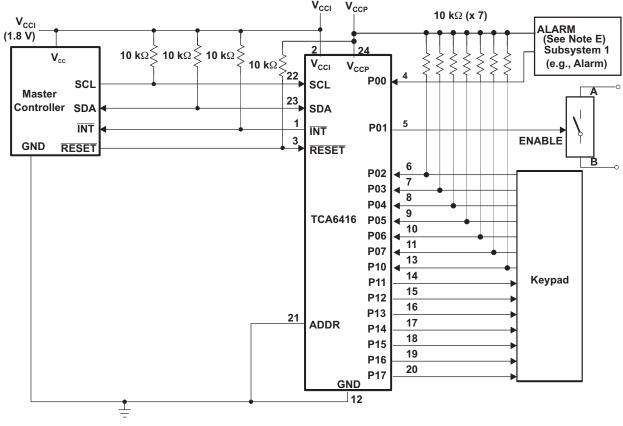
Figure 13. Reset Load Circuits and Voltage Waveforms

PRODUCT PREVIEW



# **APPLICATION INFORMATION**

Figure 14 shows an application in which the TCA6416 can be used.



- A. Device address configured as 0100000 for this example.
- B. P00 and P02-P10 are configured as inputs.
- C. P01 and P11-P17 are configured as outputs.
- D. Pin numbers shown are for the PW package.
- E. Resistors are required for inputs (on P port) that may float. If a driver to an input will never let the input float, a resistor is not needed. Outputs (in the P port) do not need pullup resistors.

Figure 14. Typical Application

# TCA6416 LOW-VOLTAGE 16-BIT I<sup>2</sup>C AND SMBus I/O EXPANDER WITH INTERRUPT OUTPUT, RESET, AND CONFIGURATION REGISTERS



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# Minimizing I<sub>CC</sub> When I/Os Control LEDs

When the I/Os are used to control LEDs, normally they are connected to  $V_{CC}$  through a resistor as shown in Figure 14. The LED acts as a diode so, when the LED is off, the I/O  $V_{IN}$  is about 1.2 V less than  $V_{CC}$ . The  $\Delta I_{CC}$  parameter in Electrical Characteristics shows how  $I_{CC}$  increases as  $V_{IN}$  becomes lower than  $V_{CC}$ . Designs that must minimize current consumption, such as battery power applications, should consider maintaining the I/O pins greater than or equal to  $V_{CC}$  when the LED is off.

Figure 15 shows a high-value resistor in parallel with the LED. Figure 16 shows  $V_{CC}$  less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O  $V_{IN}$  at or above  $V_{CC}$  and prevent additional supply current consumption when the LED is off.

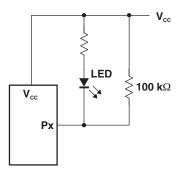


Figure 15. High-Value Resistor in Parallel With the LED

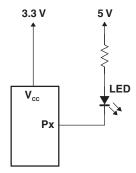


Figure 16. Device Supplied by a Low Voltage

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# **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TCA6416PW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TCA6416PWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TCA6416PWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TCA6416PWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TCA6416PWT	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TCA6416PWTG4	ACTIVE	TSSOP	PW	24	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TCA6416RTWR	PREVIEW	QFN	RTW	24	3000	TBD	Call TI	Call TI
TCA6416ZQSR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQS	24	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

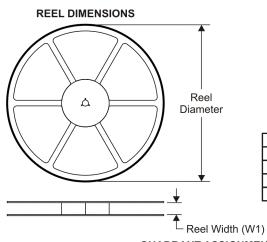
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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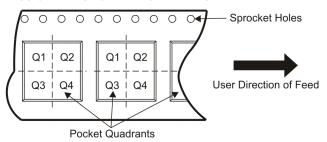
# TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



# \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA6416PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
TCA6416PWT	TSSOP	PW	24	250	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
TCA6416ZQSR	BGA MI CROSTA R JUNI OR	ZQS	24	2500	330.0	12.4	3.3	3.3	1.6	8.0	12.0	Q1



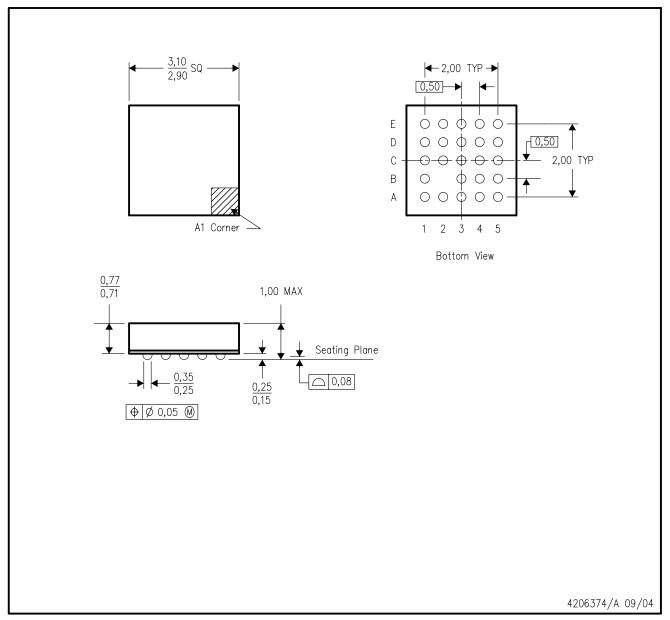


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA6416PWR	TSSOP	PW	24	2000	346.0	346.0	33.0
TCA6416PWT	TSSOP	PW	24	250	346.0	346.0	33.0
TCA6416ZQSR	BGA MICROSTAR JUNIOR	ZQS	24	2500	340.5	338.1	20.6

# ZQS (S-PBGA-N24)

# PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225
- D. This package is lead-free.



# PW (R-PDSO-G\*\*)

# 14 PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE

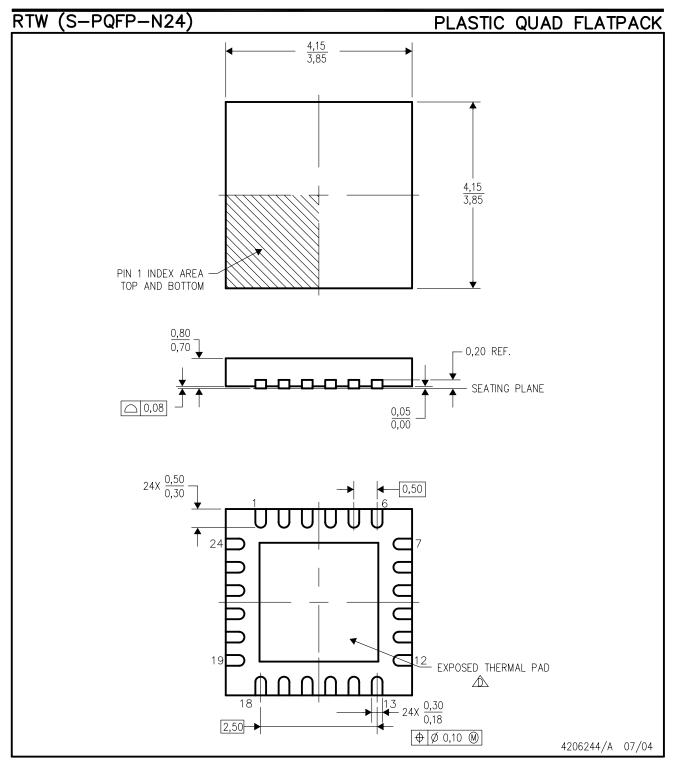


NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



- NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994.
  - B. This drawing is subject to change without notice.
  - C. Quad Flatpack, No-Leads (QFN) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - E. Falls within JEDEC MO-220.



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